FAIRCHILD SEMICONDUCTOR®

February 2006

74LCX573
Low Voltage Octal Latch with 5V Tolerant Inputs and Outputs

Features

- 5V tolerant inputs and outputs
- 2.3V–3.6V V_{CC} specifications provided
- 7.0 ns t_{PD} max (V_{CC} = 3.3V), 10µA I_{CC} max
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal[1]
- ±24mA output drive (V_{CC} = 3.0V)
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds JEDEC 78 conditions
- ESD performance
  - Human body model > 2000V
  - Machine model > 200V
- Leadless Pb-Free DQFN package

General Description

The LCX573 is a high-speed octal latch with buffered common Latch Enable (LE) and buffered common Output Enable ($\overline{OE}$) input.

The LCX573 is functionally identical to the LCX373 but has inputs and outputs on opposite sides.

The LCX573 is designed for low voltage applications with capability of interfacing to a 5V signal environment. The LCX573 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

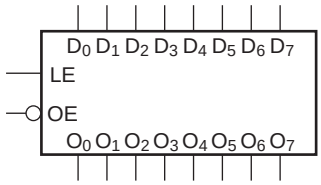
Ordering Information

Order Number	Package Number	Package Description
74LCX573WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LCX573SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LCX573BQX[2]	MLP020B	Pb-Free 20-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 4.5mm
74LCX573MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
74LCX573MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74LCX573MTCX_NL[3]	MTC20	Pb-Free 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.
Pb-Free package per JEDEC J-STD-020B.

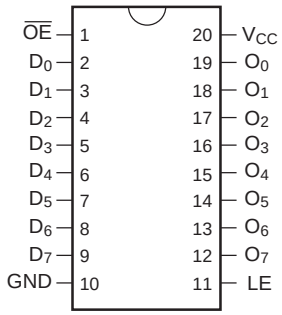
Notes
1. To ensure the high impedance state during power up or down, $\overline{OE}$ should be tied to V_{CC} through a pull-up resistor: the minimum value of the resistor is determined by the current-sourcing capability of the driver.
2. DQFN package available in Tape and Reel only.
3. "_NL" indicates Pb-Free package (per JEDEC J-STD-020B). Device available in Tape and Reel only.

Logic Symbol

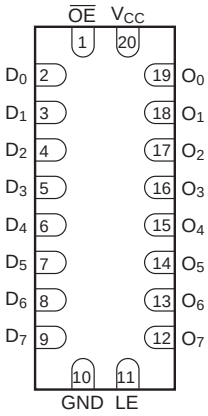


Connection Diagrams

Pin Assignments for SOIC, SOP, SSOP, TSSOP



Pad Assignments for DQFN



(Top View)

Pin Descriptions

Pin Names	Description
D_0–D_7	Data Inputs
LE	Latch Enable Input
$\overline{OE}$	3-STATE Output Enable Input
O_0–O_7	3-STATE Latch Outputs

Truth Table

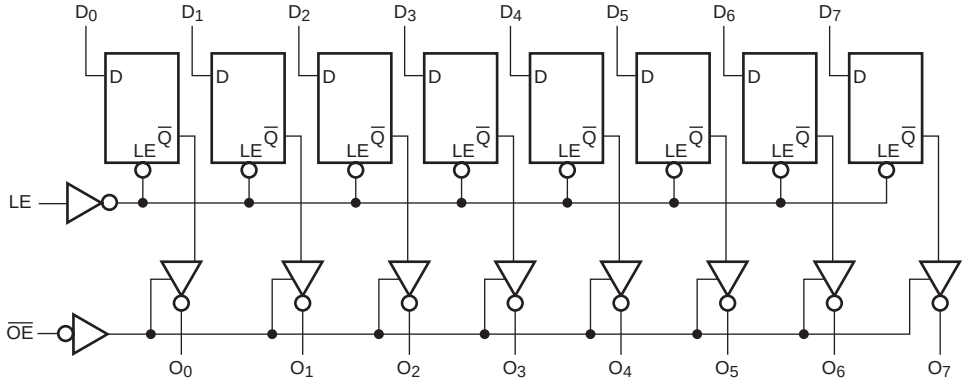
Inputs			Outputs
$\overline{OE}$	LE	D	O_n
L	H	H	H
L	H	L	L
L	L	X	O_0
H	X	X	Z

H = HIGH Voltage
L = LOW Voltage
Z = High Impedance
X = Immaterial
O_0 = Previous O_0 before HIGH-to-LOW transition of Latch Enable

Functional Description

The LCX573 contains eight D-type latches with 3-STATE output buffers. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-STATE buffers are controlled by the Output Enable ($\overline{OE}$) input. When $\overline{OE}$ is LOW, the buffers are enabled. When $\overline{OE}$ is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings

The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Symbol	Parameter	Conditions	Value	Units
V_{CC}	Supply Voltage		–0.5 to +7.0	V
V_I	DC Input Voltage		–0.5 to +7.0	V
V_O	DC Output Voltage	Output in 3-STATE	–0.5 to +7.0	V
		Output in HIGH or LOW State[4]	–0.5 to V_{CC} + 0.5	
I_{IK}	DC Input Diode Current	V_I < GND	–50	mA
I_{OK}	DC Output Diode Current	V_O < GND	–50	mA
		V_O > V_{CC}	+50	
I_O	DC Output Source/Sink Current		±50	mA
I_{CC}	DC Supply Current per Supply Pin		±100	mA
I_{GND}	DC Ground Current per Ground Pin		±100	mA
T_{STG}	Storage Temperature		–65 to +150	°C

Recommended Operating Conditions[5]

Symbol	Parameter	Conditions	Min.	Max.	Units
V_{CC}	Supply Voltage	Operating	2.0	3.6	V
		Data Retention	1.5	3.6	
V_I	Input Voltage		0	5.5	V
V_O	Output Voltage	HIGH or LOW State	0	V_{CC}	V
		3-STATE	0	5.5	
I_{OH}/I_{OL}	Output Current	V_{CC} = 3.0V – 3.6V		±24	mA
		V_{CC} = 2.7V – 3.0V		±12	
		V_{CC} = 2.3V – 2.7V		±8	
T_A	Free-Air Operating Temperature		–40	85	°C
$\Delta t/\Delta V$	Input Edge Rate	V_{IN} = 0.8V – 2.0V, V_{CC} = 3.0V	0	10	ns/V

Notes:
4. I_O Absolute Maximum Rating must be observed.
5. Unused (inputs or I/Os) must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	Conditions	V_{CC} (V)	$T_A = -40°C$ to $+85°C$		Units
				Min.	Max.	
V_{IH}	HIGH Level Input Voltage		2.3 – 2.7	1.7		V
			2.7 – 3.6	2.0		
V_{IL}	LOW Level Input Voltage		2.3 – 2.7		0.7	V
			2.7 – 3.6		0.8	
V_{OH}	HIGH Level Output Voltage	$I_{OH} = -100\mu A$	2.3 – 3.6	$V_{CC} - 0.2$		V
		$I_{OH} = -8mA$	2.3	1.8		
		$I_{OH} = -12mA$	2.7	2.2		
		$I_{OH} = -18mA$	3.0	2.4		
		$I_{OH} = -24mA$	3.0	2.2		
V_{OL}	LOW Level Output Voltage	$I_{OL} = 100\mu A$	2.3 – 3.6		0.2	V
		$I_{OL} = 8mA$	2.3		0.6	
		$I_{OL} = 12mA$	2.7		0.4	
		$I_{OL} = 16mA$	3.0		0.4	
		$I_{OL} = 24mA$	3.0		0.55	
I_I	Input Leakage Current	$0 \le V_I \le 5.5V$	2.3 – 3.6		±5.0	μA
I_{OZ}	3-STATE Output Leakage	$0 \le V_O \le 5.5V$, $V_I = V_{IH}$ or V_{IL}	2.3 – 3.6		±5.0	μA
I_{OFF}	Power-Off Leakage Current	V_I or $V_O = 5.5V$	0		10	μA
I_{CC}	Quiescent Supply Current	$V_I = V_{CC}$ or GND	2.3 – 3.6		10	μA
		$3.6V \le V_I, V_O \le 5.5V$[6]	2.3 – 3.6		±10	
ΔI_{CC}	Increase in I_{CC} per Input	$V_{IH} = V_{CC} - 0.6V$	2.3 – 3.6		500	μA

AC Electrical Characteristics

Symbol	Parameter	$T_A = -40°C$ to $+85°C$, $R_L = 500\ \Omega$						Units
		$V_{CC} = 3.3V \pm 0.3V$		$V_{CC} = 2.7V$		$V_{CC} = 2.5 \pm 0.2V$		
		$C_L = 50pF$		$C_L = 50pF$		$C_L = 30pF$		
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{PHL}, t_{PLH}	Propagation Delay, D_n to O_n	1.5	8.0	1.5	9.0	1.5	9.6	ns
t_{PHL}, t_{PLH}	Propagation Delay, LE to O_n	1.5	8.5	1.5	9.5	1.5	10.5	ns
t_{PZL}, t_{PZH}	Output Enable Time	1.5	8.5	1.5	9.5	1.5	10.5	ns
t_{PLZ}, t_{PHZ}	Output Disable Time	1.5	6.5	1.5	7.0	1.5	7.8	ns
t_S	Setup Time, D_n to LE	2.5		2.5		4.0		ns
t_H	Hold Time, D_n to LE	1.5		1.5		2.0		ns
t_W	LE Pulse Width	3.3		3.3		4.0		ns
t_{OSHL}, t_{OSLH}	Output to Output Skew[7]		1.0					ns

Notes:

6. Outputs disabled or 3-STATE only.
7. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

Symbol	Parameter	Conditions	V_{CC} (V)	T_A = 25°C Typical	Units
V_{OLP}	Quiet Output Dynamic Peak V_{OL}	C_L = 50pF, V_{IH} = 3.3V, V_{IL} = 0V	3.3	0.8	V
		C_L = 30pF, V_{IH} = 2.5V, V_{IL} = 0V	2.5	0.6	
V_{OLV}	Quiet Output Dynamic Valley V_{OL}	C_L = 50pF, V_{IH} = 3.3V, V_{IL} = 0V	3.3	–0.8	V
		C_L = 30pF, V_{IH} = 2.5V, V_{IL} = 0V	2.5	–0.6	

Capacitance

Symbol	Parameter	Conditions	Typical	Units
C_{IN}	Input Capacitance	V_{CC} = Open, V_I = 0V or V_{CC}	7	pF
C_{OUT}	Output Capacitance	V_{CC} = 3.3V, V_I = 0V or V_{CC}	8	pF
C_{PD}	Power Dissipation Capacitance	V_{CC} = 3.3V, V_I = 0V or V_{CC}, f = 10 MHz	25	pF

AC Loading and Waveforms (Generic for LCX Family)

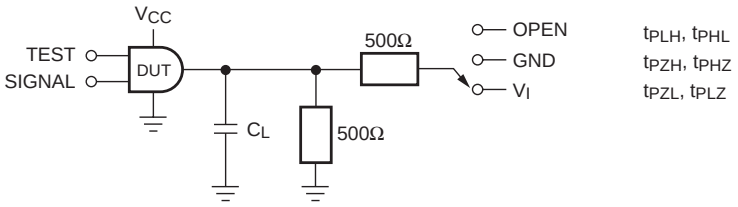
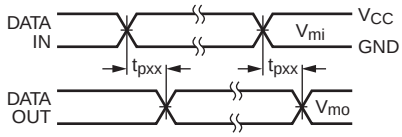
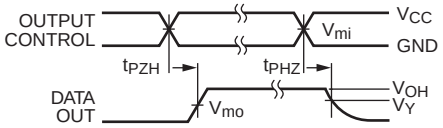


Figure 1. AC Test Circuit (C_L includes probe and jig capacitance)

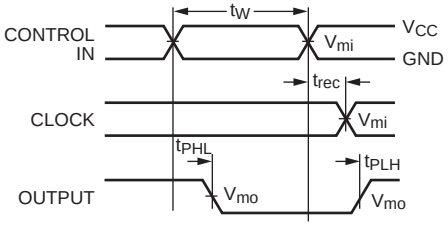
Test	Switch
t_{PLH}, t_{PHL}	Open
t_{PZL}, t_{PLZ}	6V at V_{CC} = 3.3 ± 0.3V V_{CC} x 2 at V_{CC} = 2.5 ± 0.2V
t_{PZH}, t_{PHZ}	GND



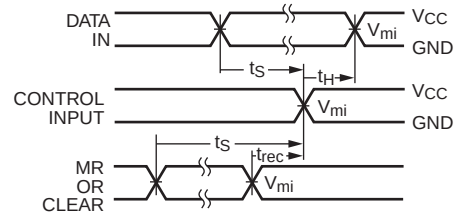
Waveform for Inverting and Non-Inverting Functions



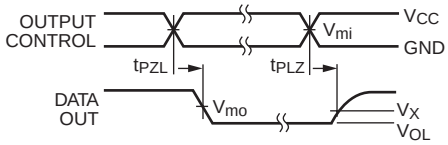
3-STATE Output High Enable and Disable Times for Logic



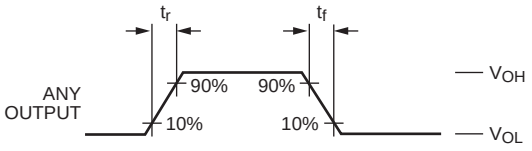
Propagation Delay, Pulse Width and t_{rec} Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic

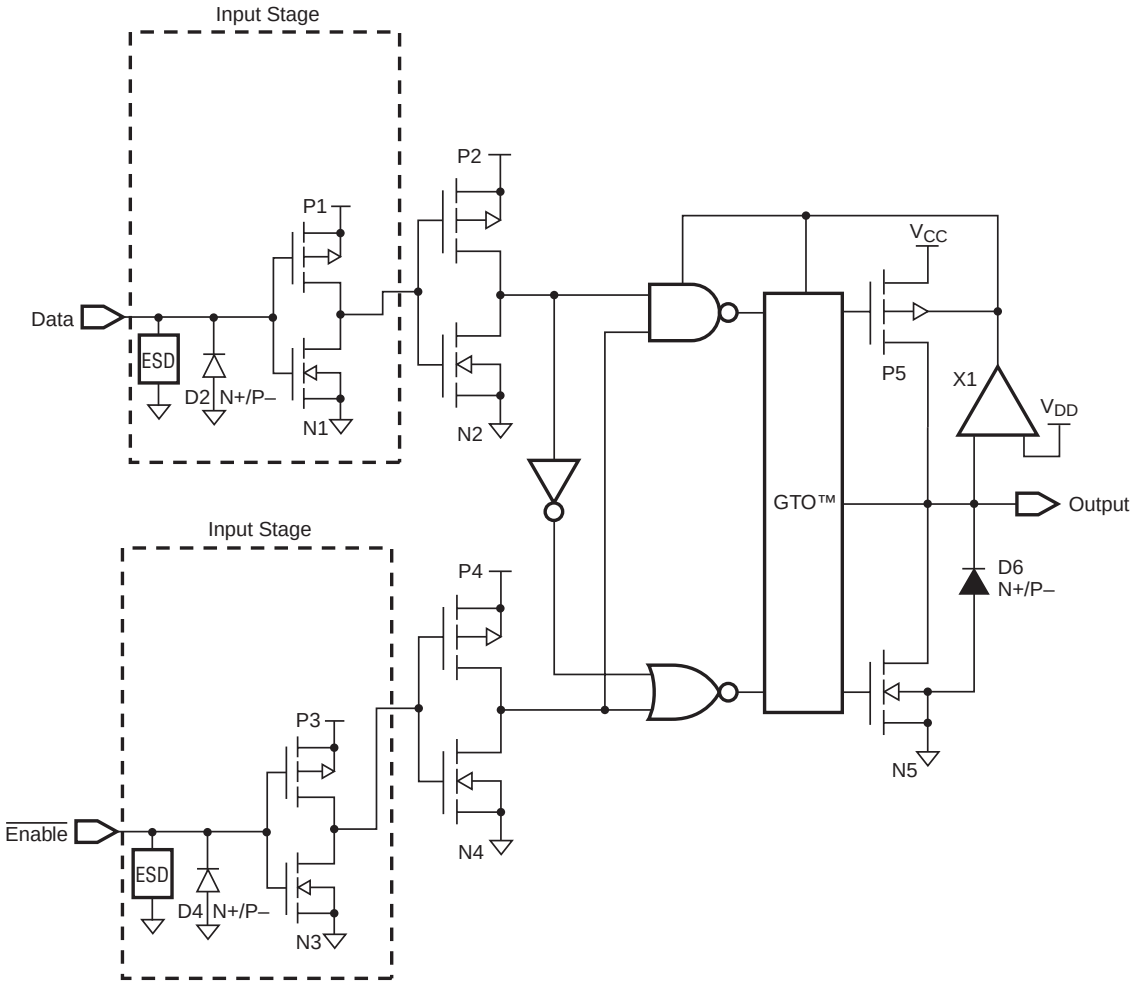


t_{rise} and t_{fall}

Figure 2. Waveforms (Input Characteristics; f = 1MHz, t_r = t_f = 3ns)

Symbol	V_{CC}		
	3.3V ± 0.3V	2.7V	2.5V ± 0.2V
V_{mi}	1.5V	1.5V	V_{CC} / 2
V_{mo}	1.5V	1.5V	V_{CC} / 2
V_x	V_{OL} + 0.3V	V_{OL} + 0.3V	V_{OL} + 0.15V
V_y	V_{OH} − 0.3V	V_{OH} − 0.3V	V_{OH} − 0.15V

Schematic Diagram (Generic for LCX Family)

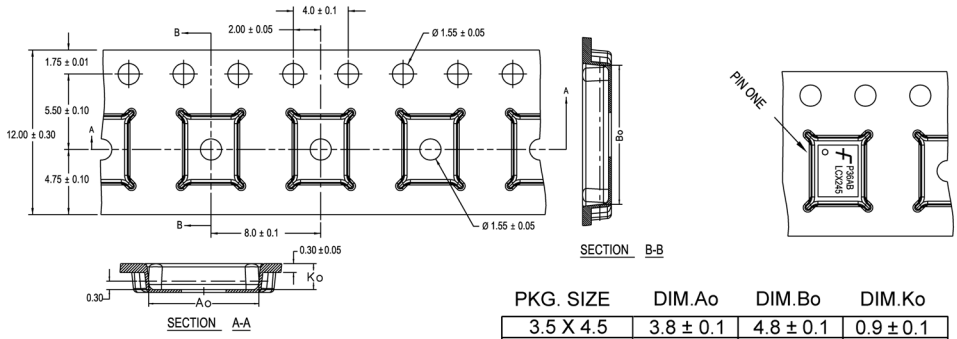


Tape and Reel Specification

Tape Format for DQFN

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
BQX	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

Tape Dimensions inches (millimeters)



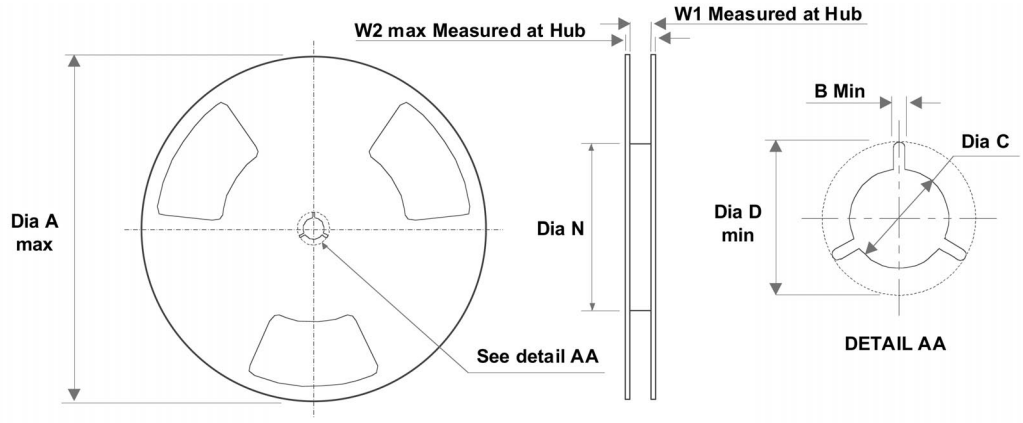
PKG. SIZE	DIM.Ao	DIM.Bo	DIM.Ko
3.5 X 4.5	3.8 ± 0.1	4.8 ± 0.1	0.9 ± 0.1
3.0 X 3.0	3.3 ± 0.1	3.3 ± 0.1	0.9 ± 0.1
2.5 X 4.5	2.8 ± 0.1	4.8 ± 0.1	0.9 ± 0.1
2.5 X 3.5	2.8 ± 0.1	3.8 ± 0.1	0.9 ± 0.1
2.5 X 3.0	2.8 ± 0.1	3.3 ± 0.1	0.9 ± 0.1
2.5 X 2.5	2.8 ± 0.1	2.8 ± 0.1	0.9 ± 0.1

DIMENSIONS ARE IN MILLIMETERS

NOTES: unless otherwise specified

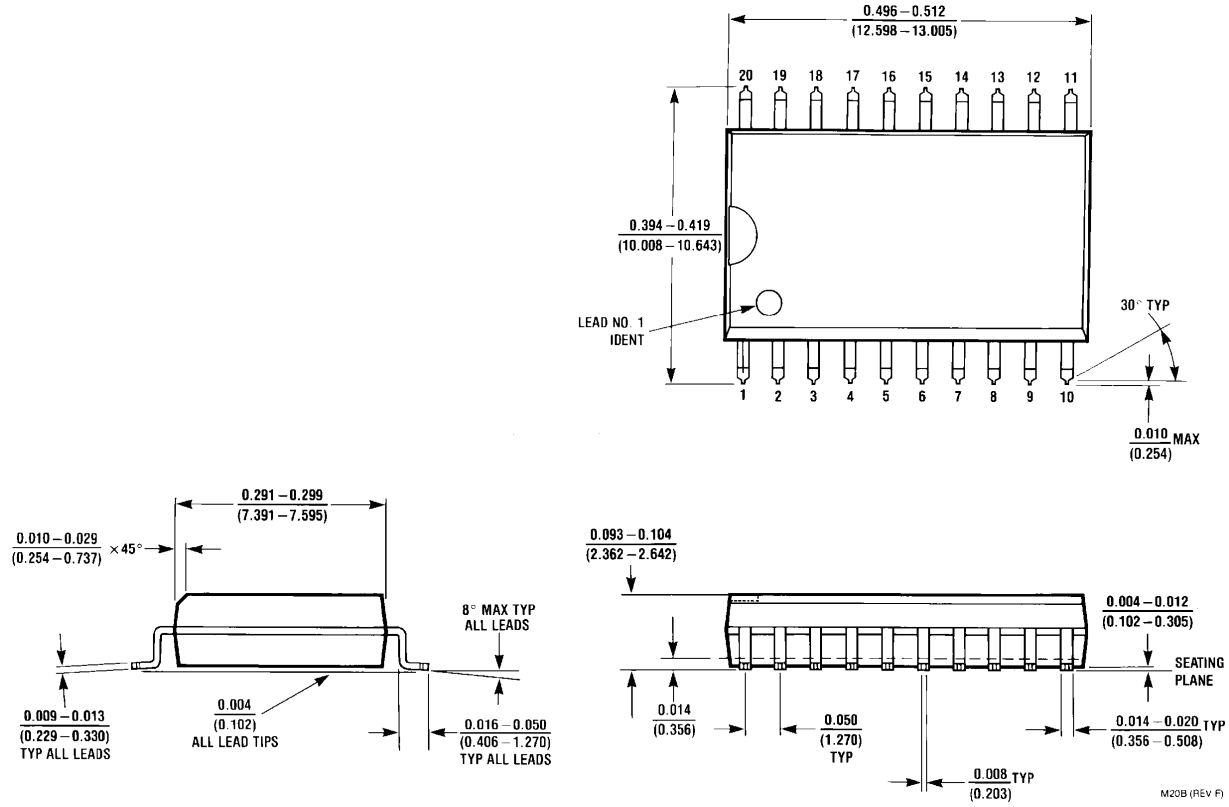
1. Cummulative pitch for feeding holes and cavities (chip pockets) not to exceed 0.008[0.20] over 10 pitch span.
2. Smallest allowable bending radius.
3. Thru hole inside cavity is centered within cavity.
4. Tolerance is ±0.002[0.05] for these dimensions on all 12mm tapes.
5. Ao and Bo measured on a plane 0.120[0.30] above the bottom of the pocket.
6. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
7. Pocket position relative to sprocket hole measured as true position of pocket. Not pocket hole.
8. Controlling dimension is millimeter. Diemension in inches rounded.

Reel Dimensions inches (millimeters)



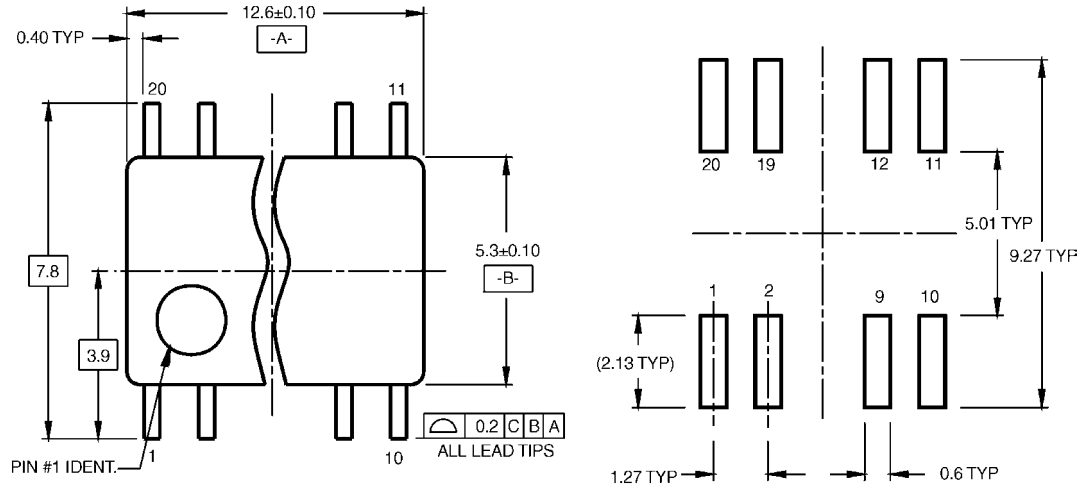
Tape Size	A	B	C	D	N	W1	W2
12 mm	13.0 (330.0)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	2.165 (55.00)	0.488 (12.4)	0.724 (18.4)

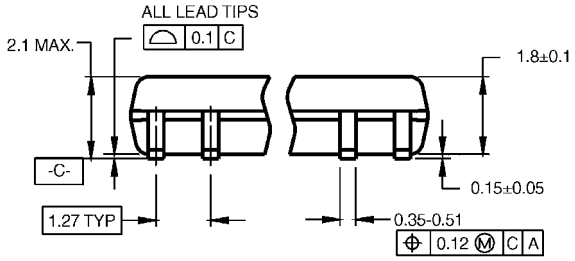
Physical Dimensions inches (millimeters) unless otherwise noted



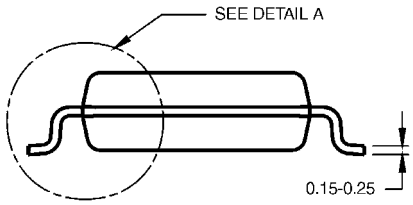
20-Lead Small Outline Integrated Circuit (SOIC),
JEDEC MS-013, 0.300" Wide Package Number M20B

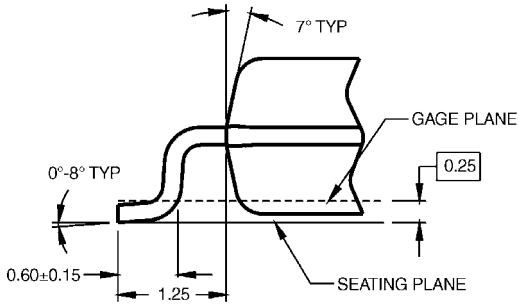
Physical Dimensions (Continued) inches (millimeters) unless otherwise noted





DIMENSIONS ARE IN MILLIMETERS





DETAIL A

NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

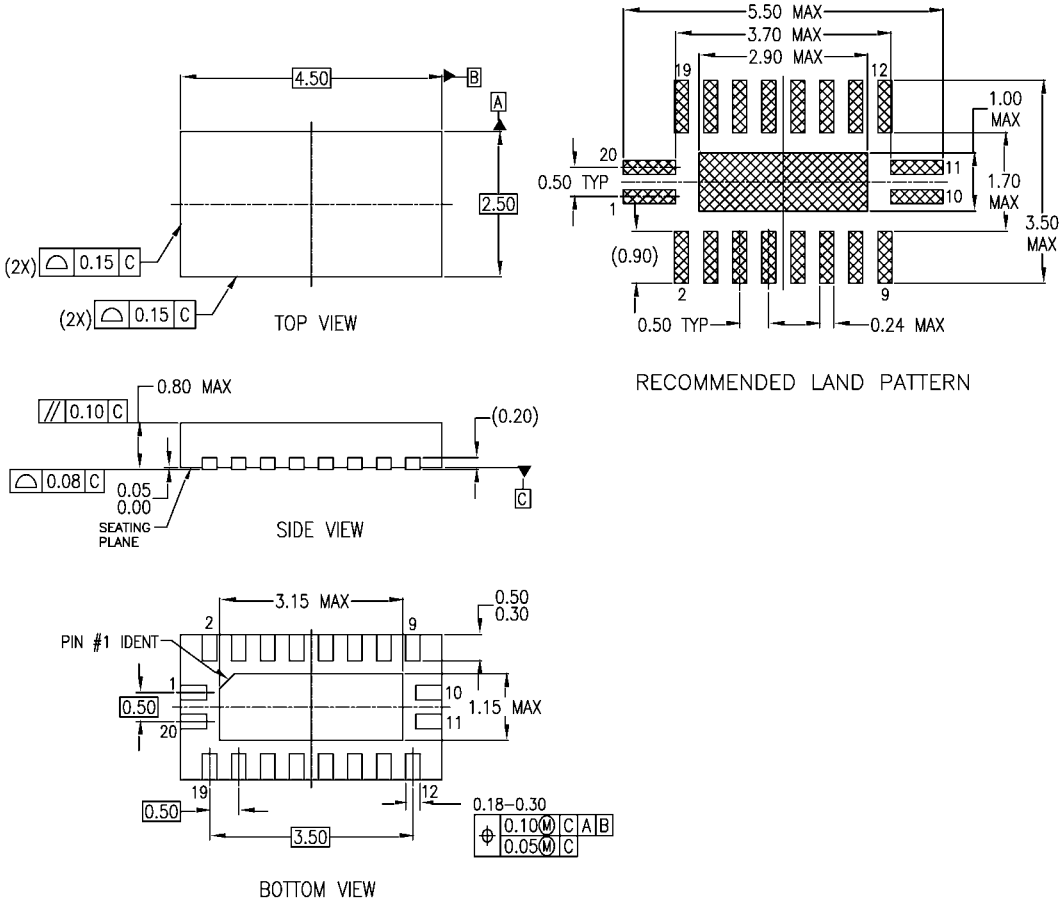
B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1

20-Lead Small Outline Package (SOP),
EIAJ TYPE II, 5.3mm Wide Package Number M20D

Physical Dimensions (Continued) inches (millimeters) unless otherwise noted



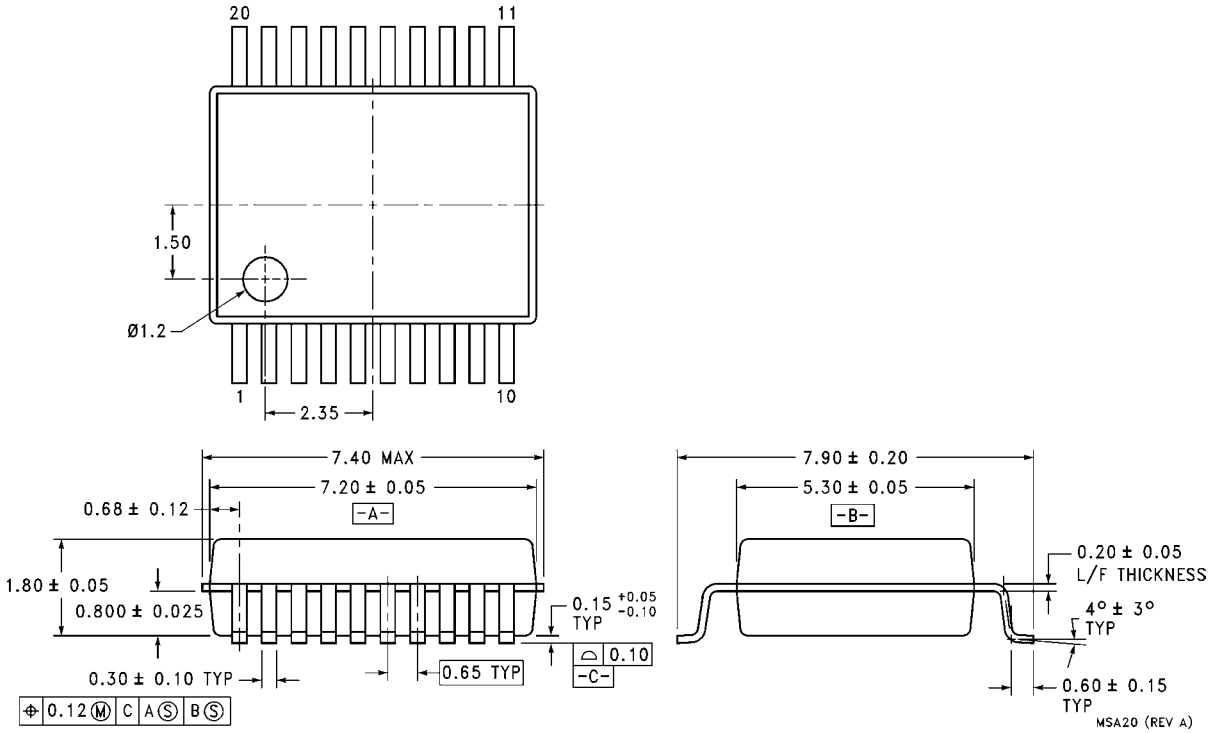
NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO–241, VARIATION AC
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP020BrevA

Pb-Free 20-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 4.5mm Package Number MLP020B

Physical Dimensions (Continued) inches (millimeters) unless otherwise noted



20-Lead Shrink Small Outline Package (SSOP),
JEDEC MO-150, 5.3mm Wide Package Number MSA20

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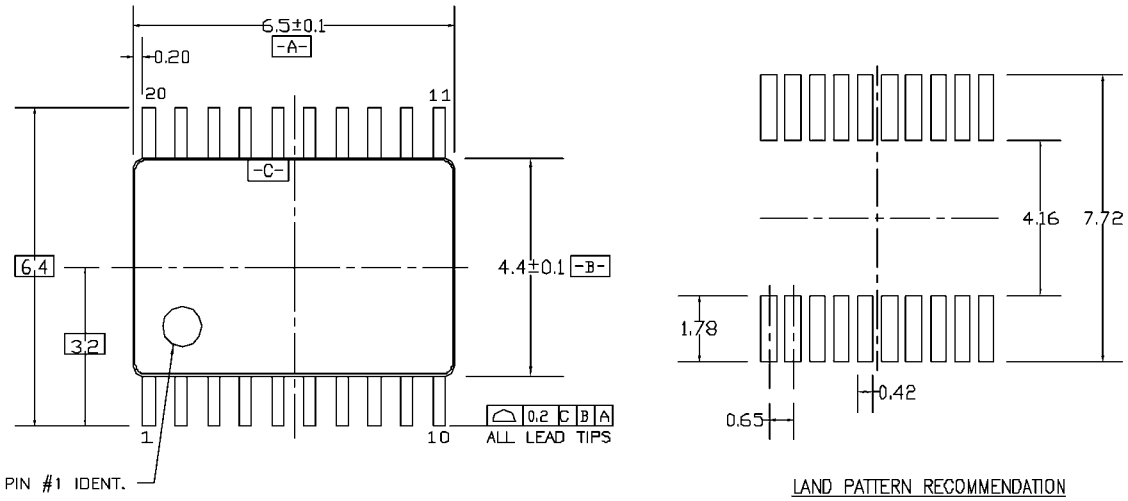
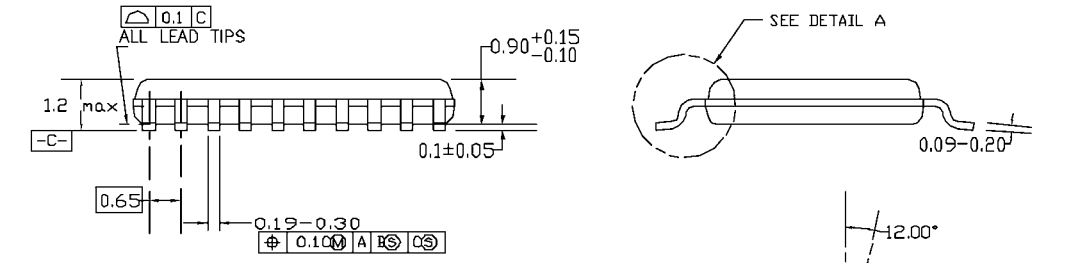
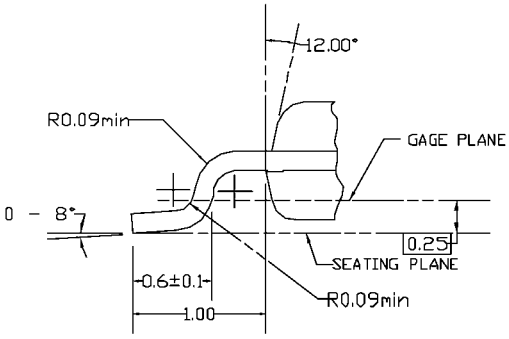




DIMENSIONS ARE IN MILLIMETERS



DETAIL A

NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO−153, VARIATION AC, REF NOTE 6, DATE 7/93.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.

D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REVD1

20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20

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Definition of Terms

Datasheet Identification	Product Status	Definition
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Rev. I18